

Heat Sink Paste | 25 g | Injection

General information

Heat sink compound suitable for PCBs in transistors, for diodes, CPUs etc.

Use it between -50 °C and 180 °C

25 g compound injection type.

Specifications

Content:	1 pc
Packaging:	Polybag



Sales information

Order code:	HSPA25I
Product description:	Heat Sink Paste 25 g Injection
Packaging:	Polybag
Brand name:	Nedis



Quantity	LxWxH (mm)			Weight
1	215 mm	30 mm	55 mm	39 g
6	250 mm	30 mm	175 mm	235 g
96	340 mm	160 mm	450 mm	4200 g
192	360 mm	350 mm	485 mm	9440 g